This book explains one of the hottest topics in wireless and electronic devices community, namely the wireless communication at mmWave frequencies, especially at the 60 GHz ISM band. It provides the reader with knowledge and techniques for mmWave antenna design, evaluation, antenna and chip packaging.

- Addresses practical engineering issues such as RF material evaluation and selection, antenna and packaging requirements, manufacturing tolerances, antenna and system interconnections, and antenna

- One of the first books to discuss the emerging research and application areas, particularly chip packages with integrated antennas, wafer scale mmWave phased arrays and imaging

- Contains a good number of case studies to aid understanding

- Provides the antenna and packaging technologies for the latest and emerging applications with the emphases on antenna integrations for practical applications such as wireless USB, wireless video, phase array, automobile collision avoidance radar, and imaging
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